

FIG. 1

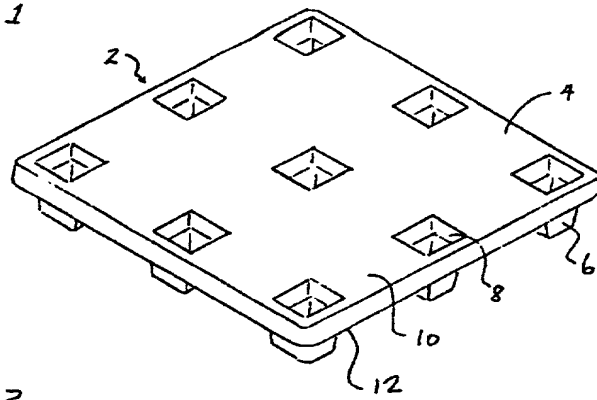


FIG. 2

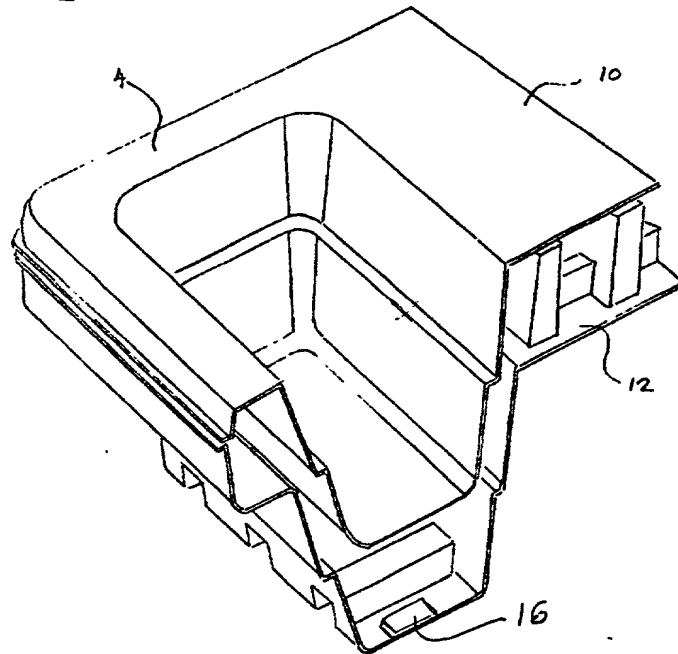


FIG. 3

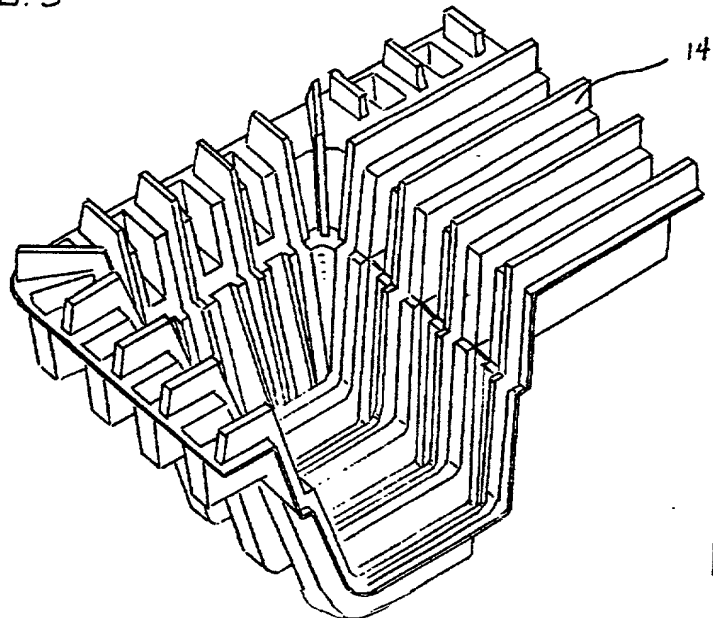


FIG. 4

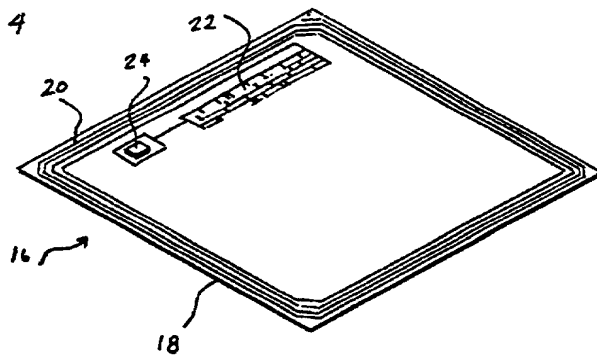


FIG. 5

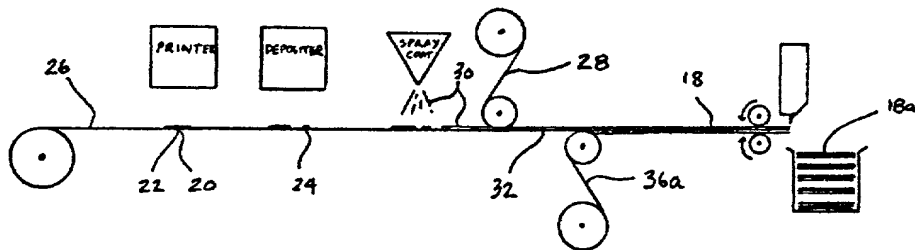


FIG. 6

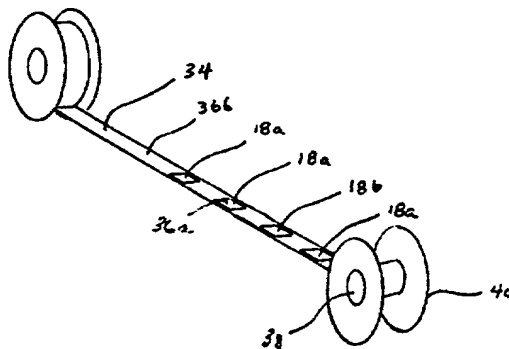


FIG. 7

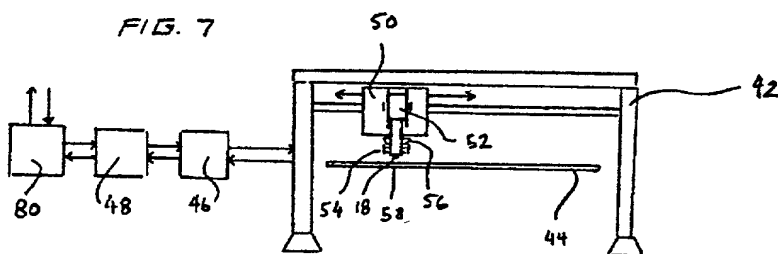


FIG. 8

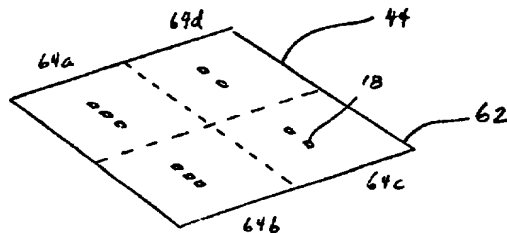


FIG. 9

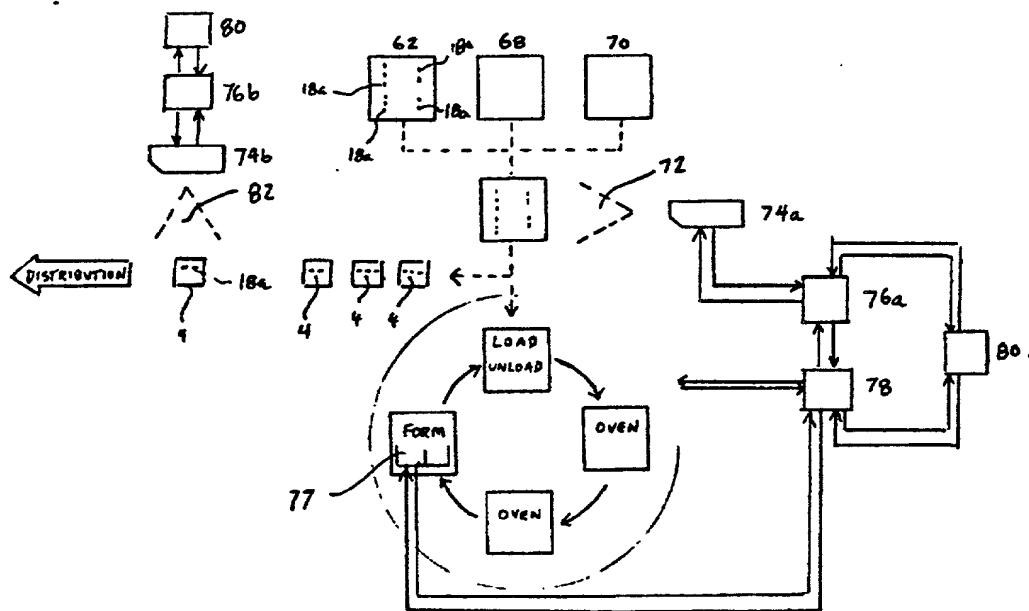


FIG. 10

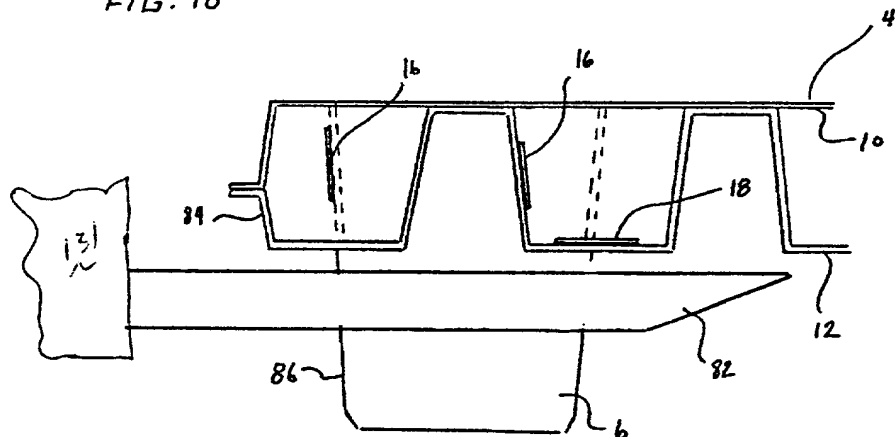


FIG. 21

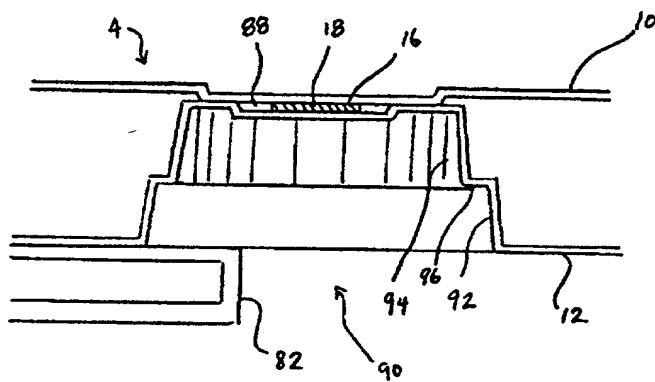


FIG. 12

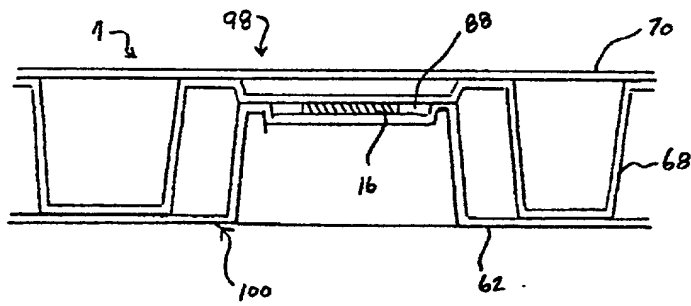


FIG. 13

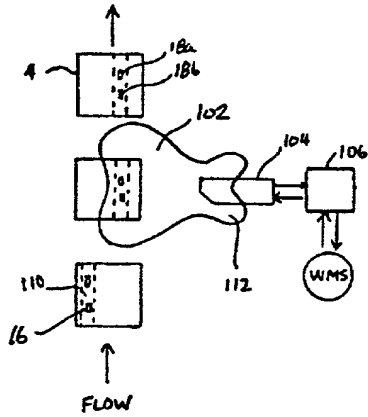


FIG. 14

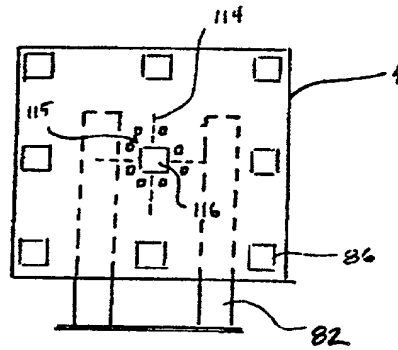


FIG. 15

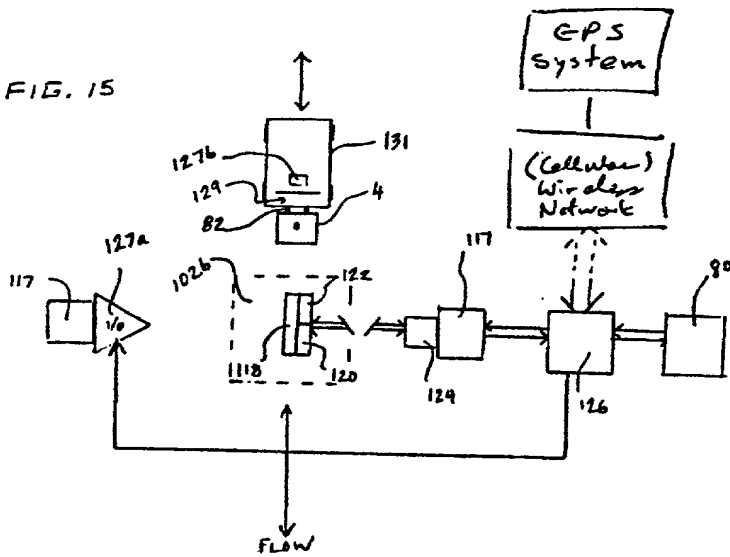


FIG. 16

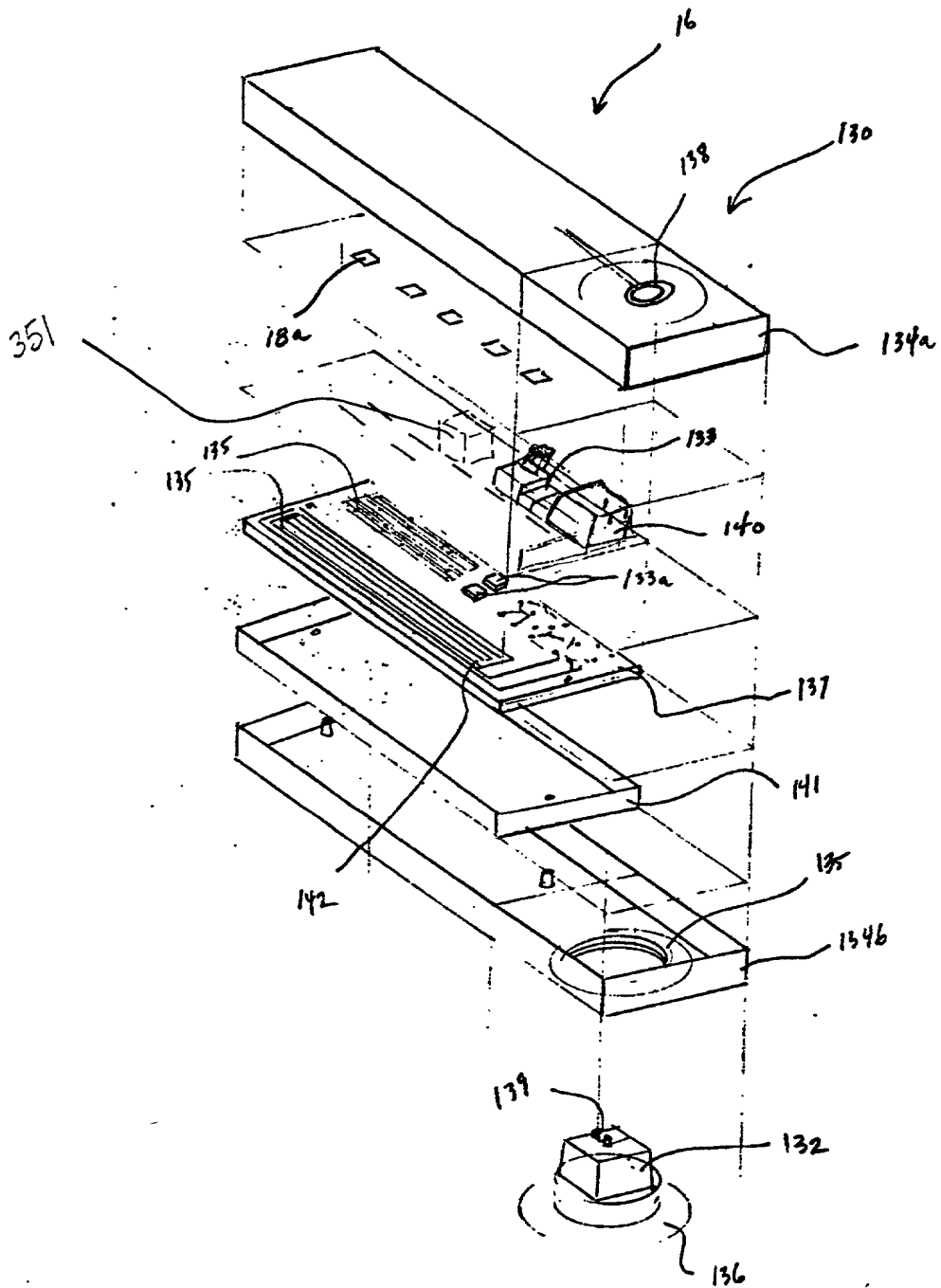
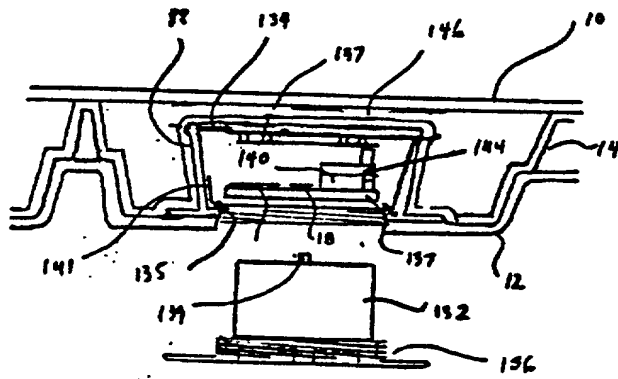


FIG. 17



351

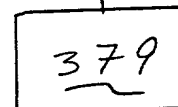
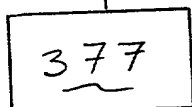
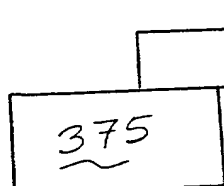
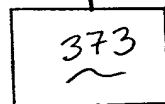
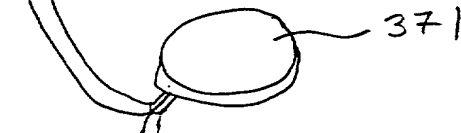
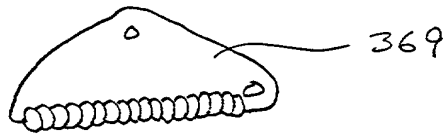
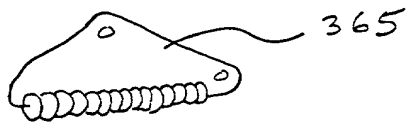
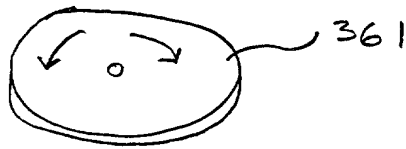
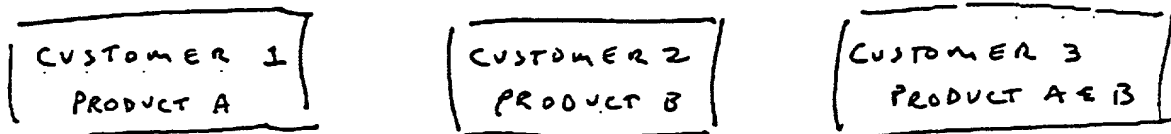


FIG. 24



SALES

ALGORITHM

NETWORK
COMPUTER

TAG MFG
PLANT

SHEET MFG
PLANT

TAGGED
SHEET

LOCAL
HOST

THERMOFORMING
MACHINE PLC

INTEROPERATION FIELD

INPUT A
(FRAME)

INPUT B
(CORNER PAD)

THERMOFORM
MACHINE
PROCESSING

PRODUCT A

PRODUCT B

PRODUCT A & B

FIG. 18

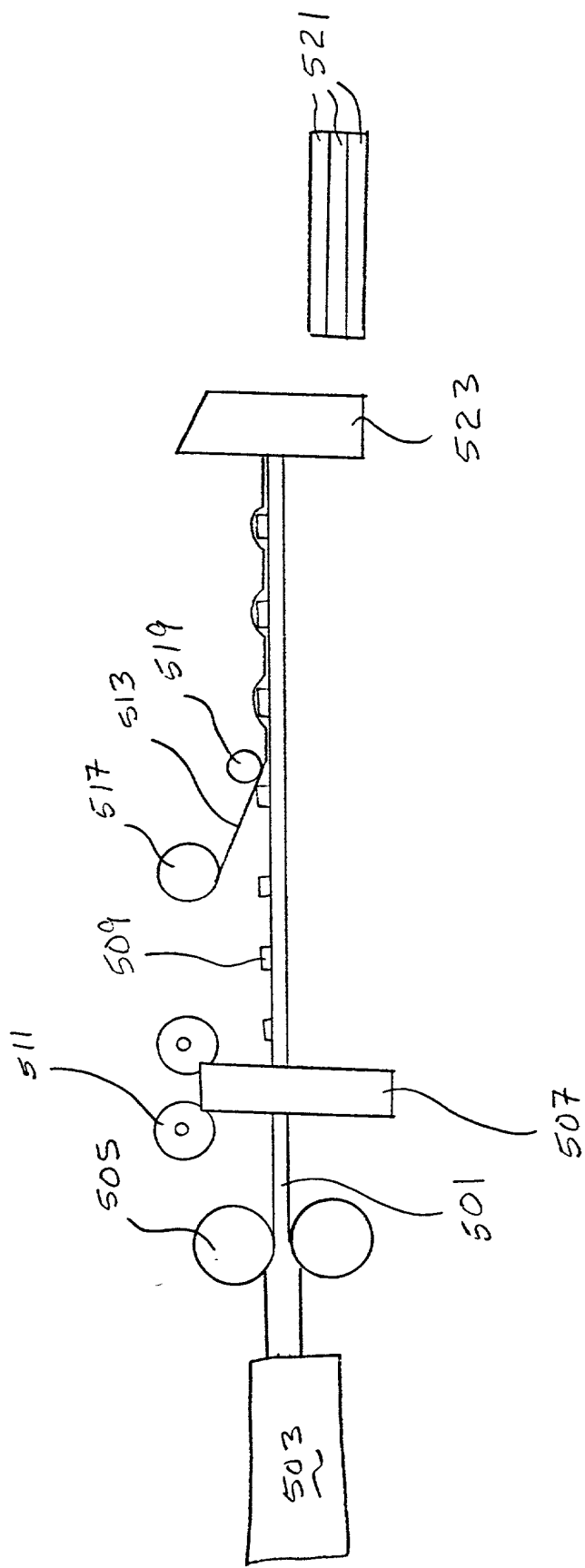
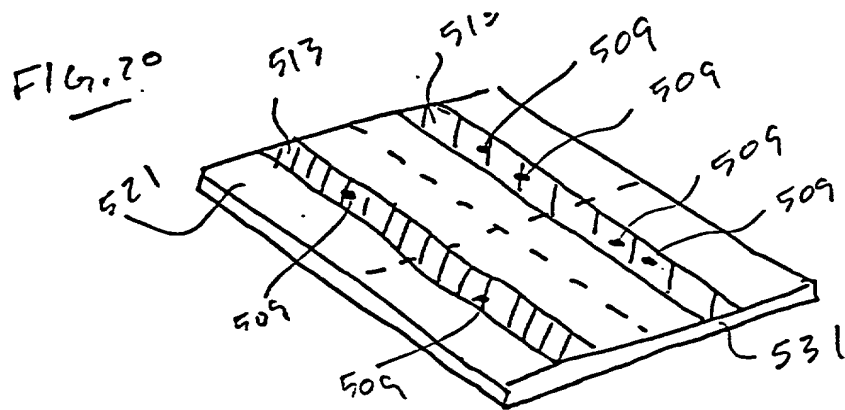


FIG. 19

FIG. 20 is a perspective view of a device 500 in a first state. The device 500 includes a substrate 501 and a plurality of conductive traces 502. The conductive traces 502 are arranged in a grid pattern. The device 500 is shown in a perspective view, with the substrate 501 and the conductive traces 502 clearly visible. The device 500 is shown in a perspective view, with the substrate 501 and the conductive traces 502 clearly visible.



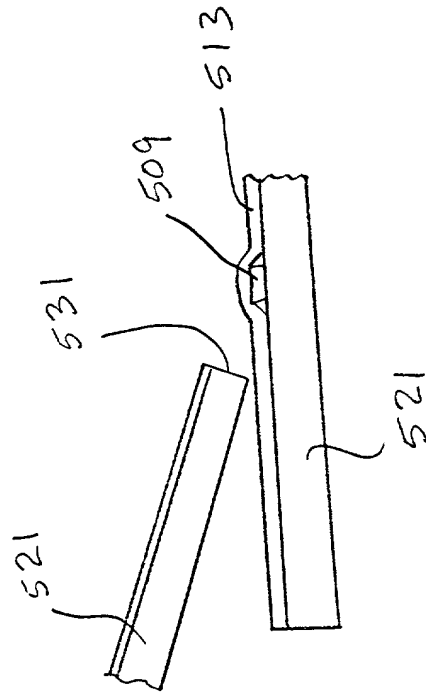
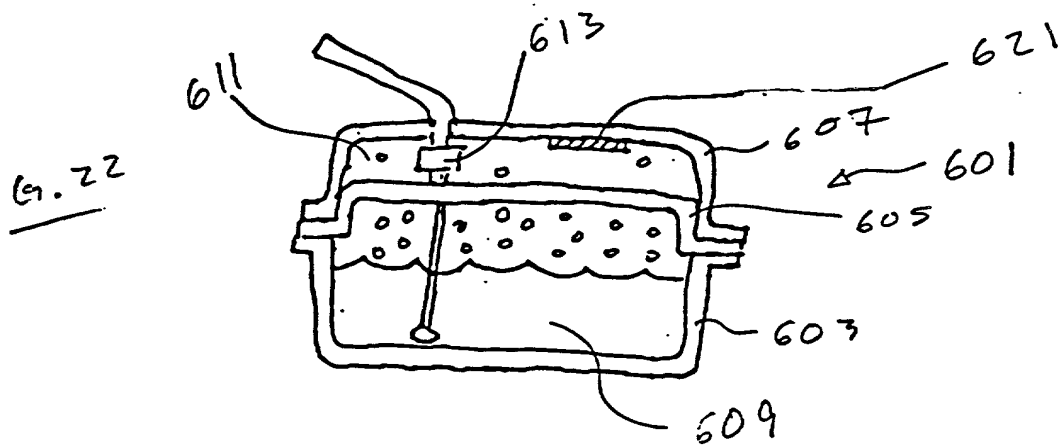


Fig. 21



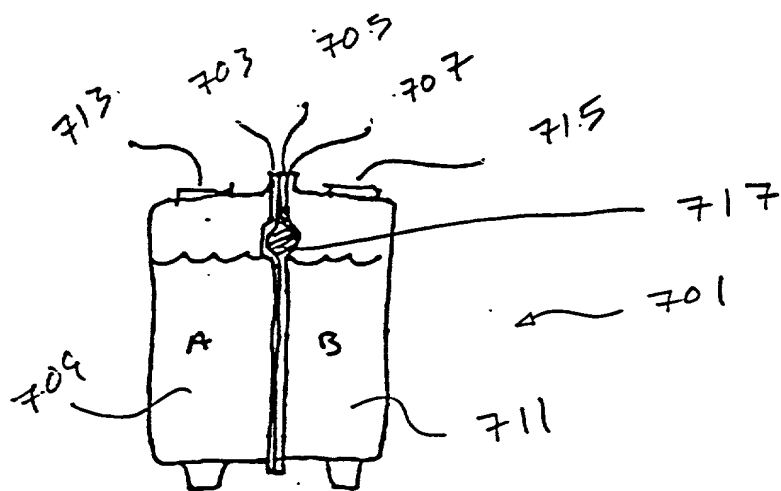


FIG. 23